

Microsemi Corporation

October 16, 2017

Product/Process Change Notification No: PPS110A060B14

Change Classification: Major

Subject: Moving wafer fab from Bend 4" to foundry 6"

Description of Change: Chips for these products are currently built in the Bend 4" wafer fab. Over the next 12 months these chips will be transferred to a 6" foundry. The Microsemi proprietary process will be transferred with as little change as possible to the process flow while fitting into the foundry's process flow and equipment capabilities.

Reason for Change: Bend wafer fab will be closing over the next 24 months.

Application Impact:

No changes to the datasheets of these products are expected with this transfer.

Method of Identifying Changed Product:

The die part number (PN) is marked on all Microsemi products affected by this change. A letter will be added to the die PN to indicate the foundry by which the chip was built.

Products Affected by this Change:

MSC part number	Description	Package
MSC010SDA120B	Schottky Diode, 1200V, 10A, RoHS	TO-247
MSC010SDA120K	Schottky Diode, 1200V, 10A, RoHS	TO-220
MSC020SDA120B	Schottky Diode, 1200V, 20A, RoHS	TO-247
MSC030SDA120B	Schottky Diode, 1200V, 30A, RoHS	TO-247
MSC030SDA120K	Schottky Diode, 1200V, 30A, RoHS	TO-220
MSC050SDA120B	Schottky Diode, 1200V, 50A, RoHS	TO-247
MSC050SDA120K	Schottky Diode, 1200V, 50A, RoHS	TO-220

Production Shipment Schedule:

There will be a transition period during which product from either wafer fab may be shipped while any inventory from the current Bend wafer fab is depleted.

Any orders for products required to be built in the current Bend wafer fab should be placed by December 31, 2017 and are required to ship by September 30, 2018.

Qualification Data:

Qualification data is not available at this time but will be made available as we achieve qualification at the foundry.

Sample availability:

Samples of the product from the 6" foundry will be made available as soon as possible with an estimated date of early 2018 for samples and qualified production units in mid-2018. Please contact your local Microsemi representative to place sample orders.

Contact Information:

Microsemi Corporation
Discrete Products Group
Power Discretes & Modules Business Unit
<http://www.microsemi.com/salescontacts>
Email: PCN_Action@microsemi.com

Regards,

Microsemi Corporation



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About Microsemi

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions; security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, Calif., and has approximately 4,800 employees globally. Learn more at www.microsemi.com.
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Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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<To be attached only where customer acknowledgement/approval is necessary prior to implementation>

CHANGE APPROVAL SUPPLEMENT

Customer Acknowledgement / Approval for

Product/Process Change Notification No: PPS110A060B14

Microsemi Corporation intends to implement this change 90 days after this notification. Acknowledgement of your company's acceptance of this change is requested per contractual agreement. Response within 30 days is required.

Accepted ☐

Rejected ☐

Signature

Date

Name

Title

Please enter rationale for rejection, if applicable: _____



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